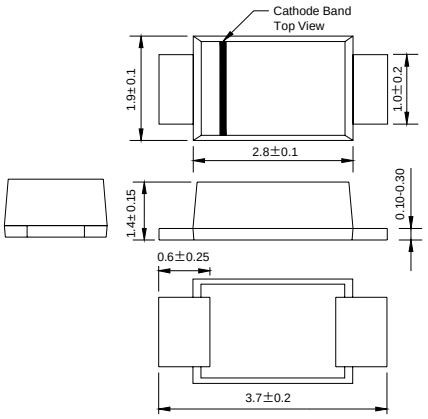
DSR0.3A-DSR0.3M

Features

- Low profile space
- Ideal for automated placement
- Glass passivated chip junctions
- Low forward voltage drop
- Low leakage current
- High forward surge capability
- High temperature soldering:
  260℃/10 seconds at terminals
- Component in accordance to
  RoHS 2002/95/1 and WEEE 2002/96/EC

SOD - 123FL



Dimensions in millimeters

Mechanical Date

- **Case:** JEDEC SOD-123FL molded plastic body over glass passivated chip
- **Terminals:** Solder plated, solderable per J-STD-002B and JESD22-B102D
- **Polarity:** Laser band denotes cathode end

Maximum Ratings & Thermal Characteristics & Electrical Characteristics

(T_A = 25 °C unless otherwise noted)

DSR-	Symbol	0.3A	0.3B	0.3D	0.3G	0.3J	0.3K	0.3M	UNIT
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	$I_{F(AV)}$	0.3							A
Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load	I_{FSM}	10							A
Maximum instantaneous forwad voltage at 0.5A	V_F	1.1							V
Maximum DC reverse current T_A = 25 ℃ at Rated DC blocking voltage T_A = 100℃	I_R	5.0 50							μ A
Typical junction capacitance at 4.0 V ,1MHz	C_J	14							p F
Operating junction and storage temperature range	T_J, T_{STG}	–55 to +150							℃

Characteristic Curves (T_A=25 ℃ unless otherwise noted)

Fig.1 Forward Current Derating Curve

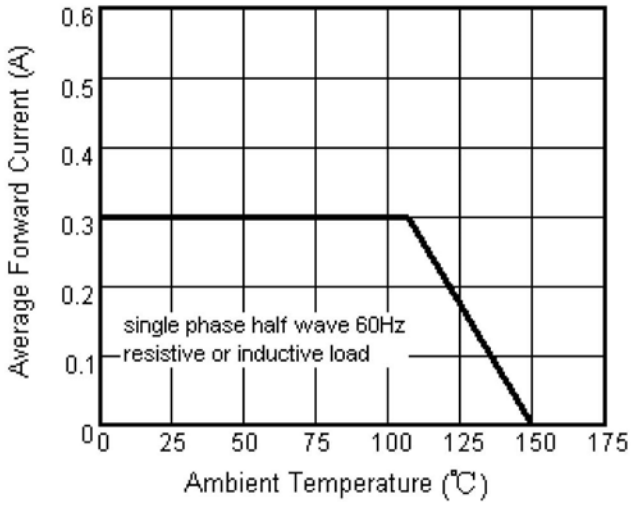


Fig.2 Maximum Non-Repetitive Peak Forward Surge Current

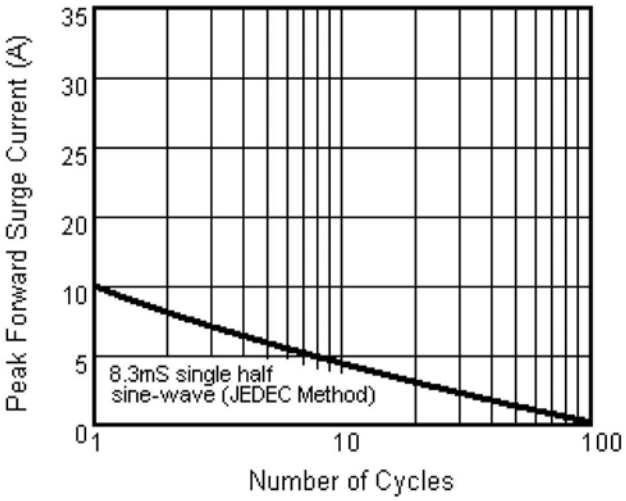


Fig.3 Typical Instantaneous Forward Characteristics

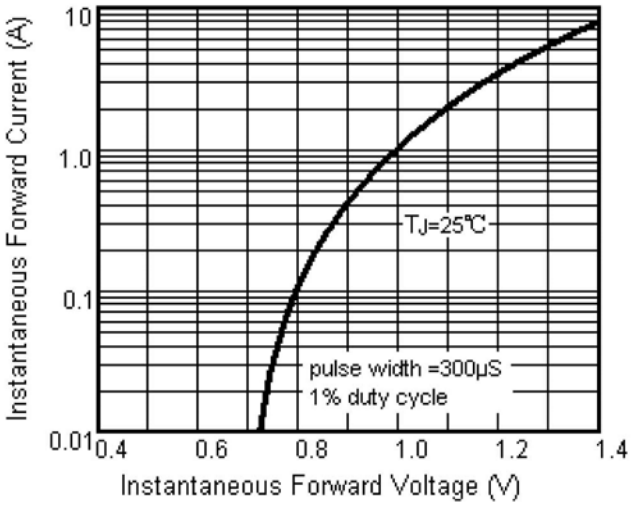


Fig.4 Typical Reverse Characteristics

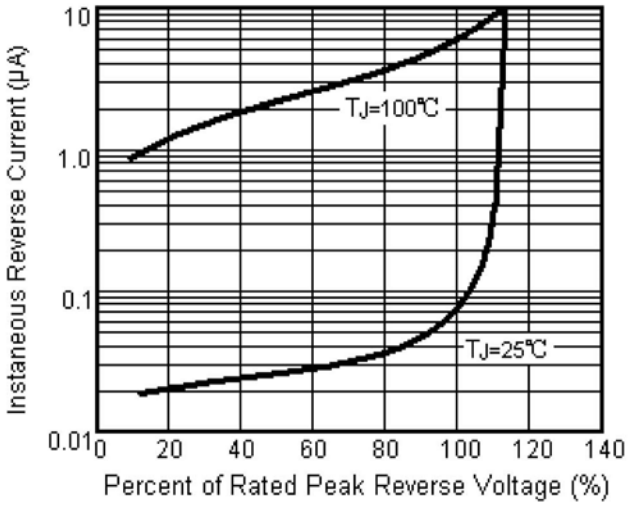


Fig.5 Typical Junction Capacitance